Fujitsu Semiconductor Limited
J-Devices Corporation

Fujitsu Semiconductor to Transfer Ownership of its LSI Assembly and Test Facilities to J-Devices

Yokohama and Usuki, Japan, August 31, 2012 - Fujitsu Semiconductor Limited (Fujitsu Semiconductor) and J-Devices Corporation (J-Devices) today announced they have signed an agreement in which Fujitsu Semiconductor will transfer ownership of LSI assembly and test facilities belonging to Fujitsu Integrated Microtechnology Limited (FIM), a wholly owned subsidiary of Fujitsu Semiconductor, to J-Devices. The objective of the agreement is for Fujitsu Semiconductor and J-Devices to build a long-term, mutually beneficial strategic partnership in the semiconductor manufacturing business. It is expected that a conclusive agreement will be signed and the transaction completed by the end of this year.

Fujitsu Semiconductor has been striving to enhance its business foundation and improve corporate management by pursuing a unique "fab-lite" business model, as announced in 2009. As part of these efforts, Fujitsu Semiconductor has been optimizing its manufacturing resources in accordance with changes in the economic and business environment.

As Japan's largest independent company devoted to semiconductor assembly and test operations for customers, J-Devices understands that, to further grow its business, it must be cost-competitive with business rivals based outside of Japan. To that end, J-Devices believes it is of the utmost importance to expand the scale of its operations.

The ownership transfer of the assembly and test facilities, therefore, is in line with the business objectives and views of both Fujitsu Semiconductor and J-Devices, leading to the signing of the agreement.

In accordance with the agreement, by the end of this year ownership of FIM's Miyagi Plant and Aizu Plant is scheduled to be transferred to J-Devices, which will then take over the operation of these manufacturing facilities. All employees of the two plants are expected to be transferred to J-Devices. In addition, FIM plans a staged transfer of equipment from its Kyushu Plant to J-Devices facilities also located in Kyushu, and ultimately will transfer all of its manufacturing capability. After the transfer is complete, the manufacturing currently conducted at FIM's Kyushu Plant will take place with the same high standards for quality at J-Devices' facilities. Employees of FIM's Kyushu Plant are scheduled to be transferred to J-Devices or reassigned within the Fujitsu Group.

The products that are currently being made at the assembly and test facilities to be transferred will be produced by J-Devices and will continue to be supplied to customers through Fujitsu Semiconductor with the same high standards for quality, delivery, and service. Based on the mutually beneficial relationship that will be created through this transaction, J-Devices seeks to continue contributing to the further progress of Japan's semiconductor industry.

Fujitsu Semiconductor Limited

Address:	2-10-23 Shin-Yokohama, Kohoku-Ku Yokohama, Kanagawa, Japan
President:	Haruki Okada
Business Operation:	Design, development, production and sales of LSI devices.
Employees:	Approximately 4,900

J-Devices Corporation

Address:	1913-2 Fukura, Usuki-shi, Oita, Japan
President:	Yoshifumi Nakaya
Business Operation:	Semiconductor packaging (assembly, test, etc.)
Employees:	Approximately 2,000

Fujitsu Integrated Microtechnology Limited

Address:	1 Takaku-kogyodanchi, Aizuwakamatsu-shi, Fukushima, Japan Miyagi Plant: 1-1 Nishigaoka, Murata, Murata-machi, Shibata-gun, Miyagi, Japan Aizu Plant: 1 Takaku-kogyodanchi, Aizuwakamatsu-shi, Fukushima, Japan (same as head office) Kyushu Plant: 5950 Iriki-cho Soeda, Satsumasendai-shi, Kagoshima, Japan
President:	Hideo Monma
Business Operation:	Assembly and testing of LSI devices
Employees:	Approximately 1,900

About Fujitsu Semiconductor

Fujitsu Semiconductor Limited designs, manufactures, and sells semiconductors, providing highly reliable, optimal solutions and support to meet the varying needs of its customers. Products and services include microcontrollers, ASICs, ASSPs, and power management ICs, with wide-ranging expertise focusing on mobile, ecological, automotive, imaging, security, and high-performance applications. Fujitsu Semiconductor also drives power efficiency and environmental initiatives. Headquartered in Yokohama, Fujitsu Semiconductor Limited (formerly named Fujitsu Microelectronics Limited) was established as a subsidiary of Fujitsu Limited on March 21, 2008. Through its global sales and development network, with sites in Japan and throughout Asia, Europe, and the Americas, Fujitsu Semiconductor offers semiconductor solutions to the global marketplace.
For more information, please see: http://jp.fujitsu.com/fsl/en/

About J-Devices Corporation

J-Devices is the largest independent semiconductor assembly and test company in Japan with four factories in Kyushu island.
The original company (named Nakaya Microdevices) was established in 1970 and offers a broad lineup of packages including thermally enhanced BGA, CMOS sensor, leadframe and other original packages.
J-Devices offers skilled package development as well as the full turnkey "one stop" service such as wafer sort, assembly, and final testing for consumer and automotive product.

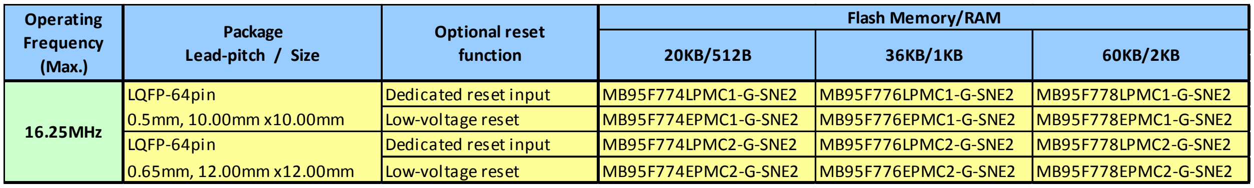
Press Contacts

Fujitsu Semiconductor Limited
Public Relations Department
Inquiry: https://www-s.fujitsu.com/jp/group/fsl/en/release/inquiry.html

Appendix

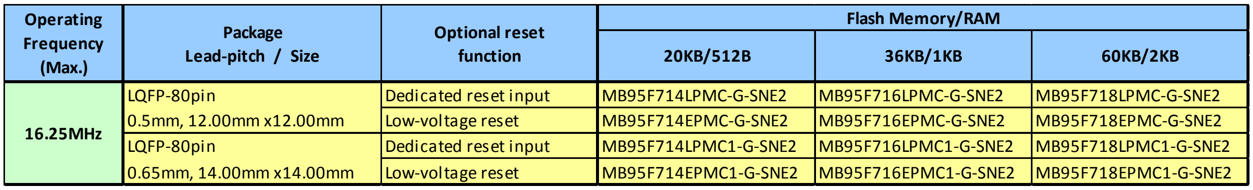
Line-Up

MB95770 series (12 Products)



Operating Frequency (Max.)	Package Lead-pitch / Size	Optional reset function	Flash Memory/RAM		
			20KB/512B	36KB/1KB	60KB/2KB
16.25MHz	LQFP-64pin	Dedicated reset input	MB95F774LPMC1-G-SNE2	MB95F776LPMC1-G-SNE2	MB95F778LPMC1-G-SNE2
	0.5mm, 10.00mm x10.00mm	Low-voltage reset	MB95F774EPMC1-G-SNE2	MB95F776EPMC1-G-SNE2	MB95F778EPMC1-G-SNE2
	LQFP-64pin	Dedicated reset input	MB95F774LPMC2-G-SNE2	MB95F776LPMC2-G-SNE2	MB95F778LPMC2-G-SNE2
	0.65mm, 12.00mm x12.00mm	Low-voltage reset	MB95F774EPMC2-G-SNE2	MB95F776EPMC2-G-SNE2	MB95F778EPMC2-G-SNE2

MB95710 Series (12 Products)



Operating Frequency (Max.)	Package Lead-pitch / Size	Optional reset function	Flash Memory/RAM		
			20KB/512B	36KB/1KB	60KB/2KB
16.25MHz	LQFP-80pin	Dedicated reset input	MB95F714LPMC-G-SNE2	MB95F716LPMC-G-SNE2	MB95F718LPMC-G-SNE2
	0.5mm, 12.00mm x12.00mm	Low-voltage reset	MB95F714EPMC-G-SNE2	MB95F716EPMC-G-SNE2	MB95F718EPMC-G-SNE2
	LQFP-80pin	Dedicated reset input	MB95F714LPMC1-G-SNE2	MB95F716LPMC1-G-SNE2	MB95F718LPMC1-G-SNE2
	0.65mm, 14.00mm x14.00mm	Low-voltage reset	MB95F714EPMC1-G-SNE2	MB95F716EPMC1-G-SNE2	MB95F718EPMC1-G-SNE2